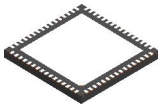


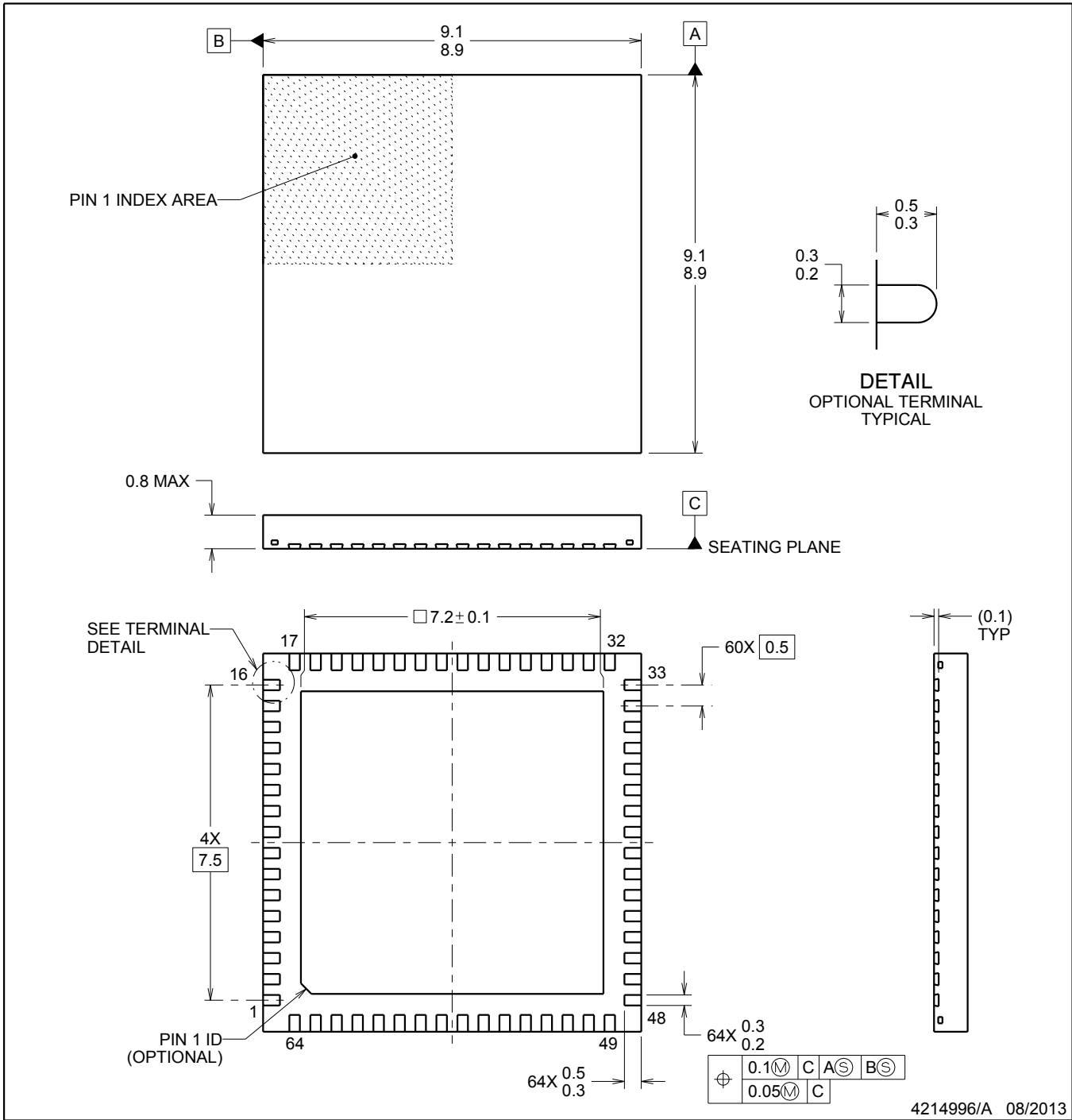
# PACKAGE OUTLINE

NKD0064A



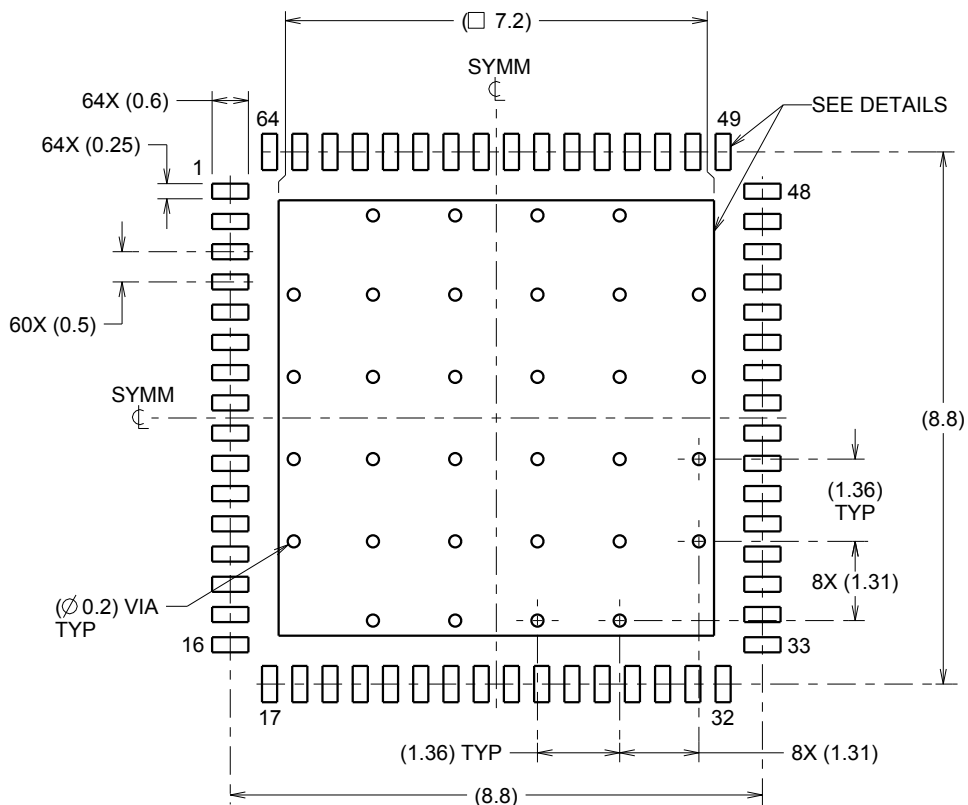
WQFN - 0.8 mm max height

WQFN

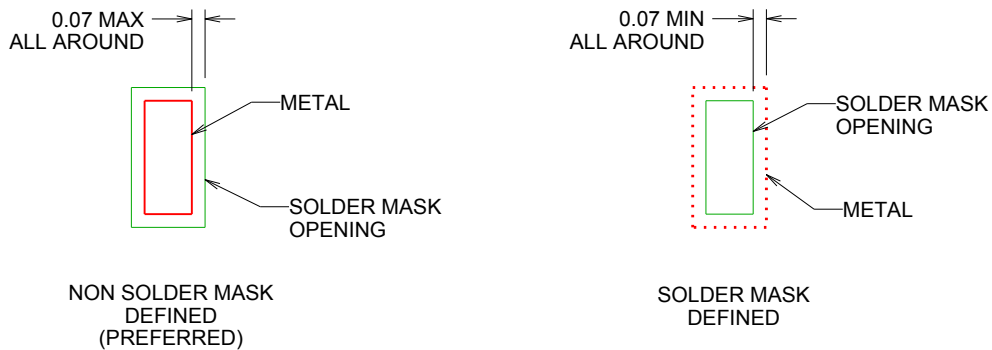


**NOTES:**

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.



LAND PATTERN EXAMPLE  
SCALE:8X

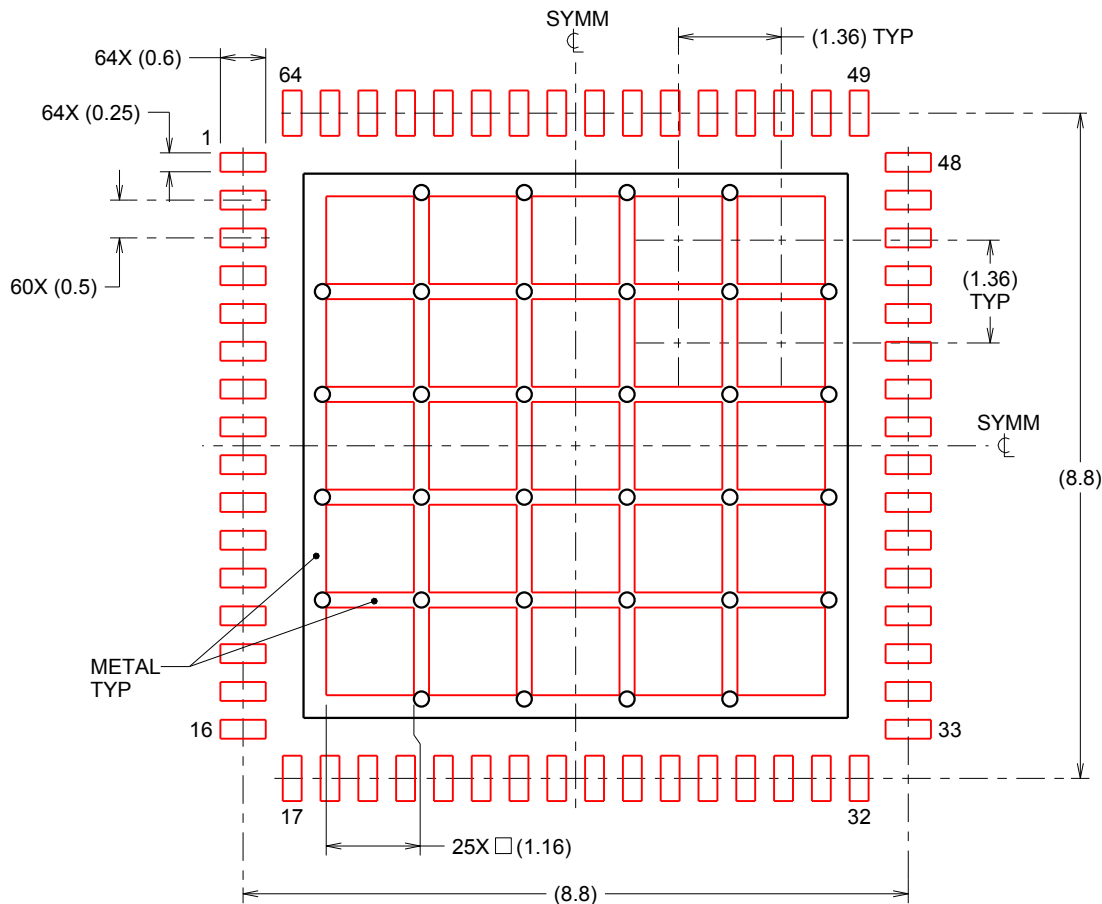


SOLDER MASK DETAILS

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NOTES: (continued)

4. This package is designed to be soldered to a thermal pad on the board. For more information, refer to QFN/SON PCB application note in literature No. SLUA271 ([www.ti.com/lit/slua271](http://www.ti.com/lit/slua271)).



**SOLDERPASTE EXAMPLE**  
 BASED ON 0.125mm THICK STENCIL  
 EXPOSED PAD  
 65% PRINTED SOLDER COVERAGE BY AREA  
 SCALE:10X

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NOTES: (continued)

5. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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